

Automotive MOSFET

OptiMOS™ 7 Power-Transistor







Features

- OptiMOS[™] power MOSFET for automotive applications
- N-channel Enhancement mode Normal Level
- Extended qualification beyond AEC-Q101
- Enhanced electrical testing
- Robust design
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- RoHS compliant
- 100% Avalanche tested

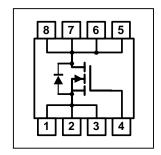
Potential applications

General automotive applications.

Product validation

Qualified for automotive applications. Product validation according to AEC-Q101.





Product Summary

V_{DS}	40	V
R _{DS(on)}	1.53	mΩ
I _D (chip limited)	173	Α

Туре	Package	Marking
IAUCN04S7N015	PG-TDSON-8-34	7N04N015

IAUCN04S7N015



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Maximum ratings

at Tj=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I _D	V _{GS} =10 V, Chip limitation ^{1,2)}	173	A
		V _{GS} =10V, DC current	120	
		T_a =100 °C, V_{GS} =10 V, R_{thJA} on 2s2p ^{2,3)}	30	
Pulsed drain current ²⁾	/ _{D,pulse}	$T_{\rm C}$ =25 °C, $t_{\rm p}$ = 100 μs	450	
Avalanche energy, single pulse ²⁾	E AS	/ _D =45 A	69	mJ
Avalanche current, single pulse	I _{AS}	-	90	А
Gate source voltage	V _{GS}	-	±20	V
Power dissipation	P _{tot}	Т _С =25 °С	88	W
Operating and storage temperature	$T_{\rm j}, T_{\rm stg}$	-	-55 +175	°C

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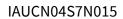
Thermal characteristics²⁾

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.]
Thermal resistance, junction - case	R thJC	-	-	0.9	1.7	K/W
Thermal resistance, junction - ambient ³⁾	R _{thJA}	-	-	28	-	

Electrical characteristics

at Tj=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Static characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0 V, I _D =1 mA	40	-	-	V
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 30 \mu A$	2.2	2.6	3.0	
Zero gate voltage drain current	I _{DSS}	$V_{\rm DS}$ =40 V, $V_{\rm GS}$ =0 V, $T_{\rm j}$ =25 °C	-	_	1	μΑ
		V_{DS} =40 V, V_{GS} =0 V, T_{j} =100 °C ²⁾	-	-	8	
Gate-source leakage current	I _{GSS}	V _{GS} =20 V, V _{DS} =0 V	-	-	100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =7 V, I _D =30 A	_	1.73	1.99	mΩ
		V _{GS} =10 V, I _D =60 A	-	1.37	1.53	
Gate resistance ²⁾	R _G	-	-	1.8	-	Ω





Parameter	Symbol Conditions		Values			Unit
			min.	typ.	max.	1
Dynamic characteristics ²⁾	•					•
Input capacitance	C iss		-	2148	2792	pF
Output capacitance	C oss	V_{GS} =0 V, V_{DS} =20 V, f =1 MHz	_	1248	1620	
Reverse transfer capacitance	C _{rss}	7	_	44	66	1
Turn-on delay time	t d(on)		_	5	_	ns
Rise time	t _r	V_{DD} =20 V, V_{GS} =10 V, I_{D} =60 A,	_	3	_	
Turn-off delay time	t d(off)	R_{G} =3.5 Ω V_{DD} =20 V, I_{D} =60 A, V_{GS} =0 to 10 V	_	12	_	
Fall time	t _f		_	7	_	
Gate to drain charge Gate charge total	Q _{gd}		-	6	10 41	
		- ∔	_	6	10	1
Gate plateau voltage	V _{plateau}	+	_	4.3	_	V
Reverse Diode				<u> </u>	I	
Diode continous forward current ²⁾	Is	<i>T</i> _C =25 °C	-	_	120	А
Diode pulse current ²⁾	I _{S,pulse}	$T_{\rm C}$ =25 °C, $t_{\rm p}$ = 100 μ s	-	-	450	
Diode forward voltage	V _{SD}	V_{GS} =0 V, I_{F} =60 A, T_{j} =25 °C	-	0.8	0.95	V
Reverse recovery time ²⁾	t _{rr}	V_R =20 V, I_F =50A, d i_F /d t =100 A/ μ s	-	27	40	ns
Reverse recovery charge ²⁾	Q rr		-	12	24	nC

¹⁾ Practically the current is limited by the overall system design including the customer-specific PCB.

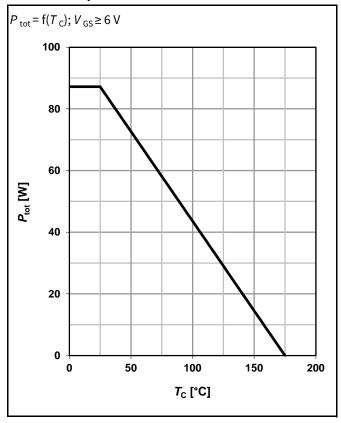
 $^{^{2)}\,\}mbox{The parameter}$ is not subject to production testing – specified by design.

³⁾ Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.

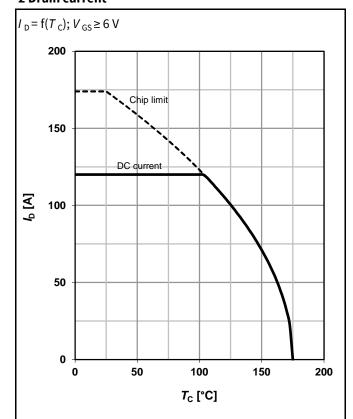


Electrical characteristics diagrams

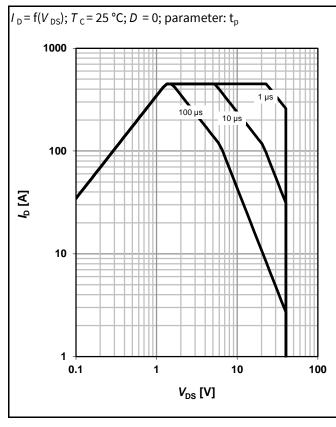
1 Power dissipation



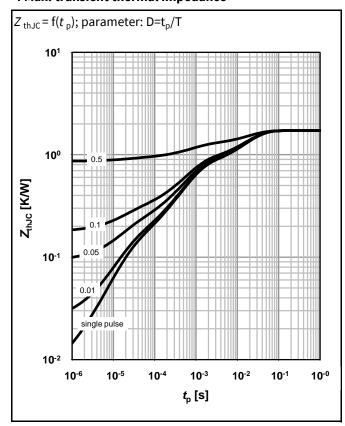
2 Drain current



3 Safe operating area

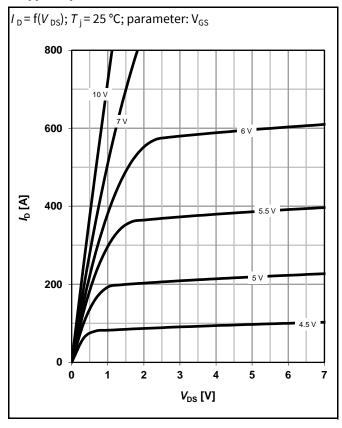


4 Max. transient thermal impedance

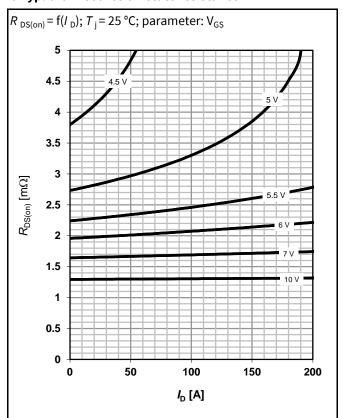




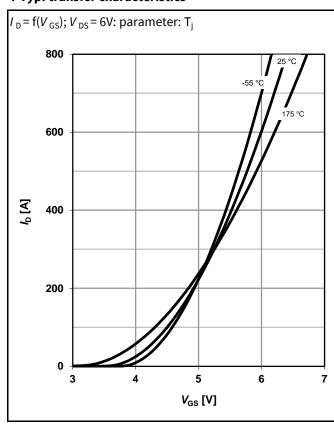
5 Typ. output characteristics



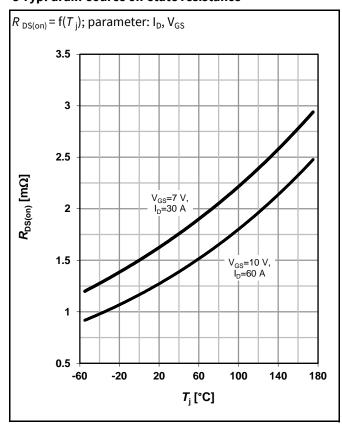
6 Typ. drain-source on-state resistance



7 Typ. transfer characteristics

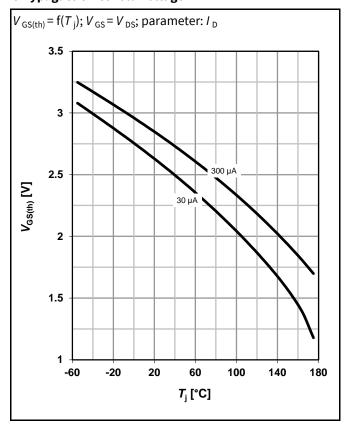


8 Typ. drain-source on-state resistance

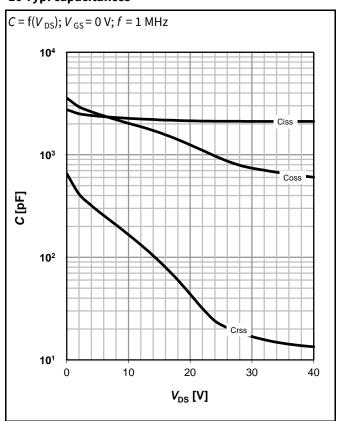


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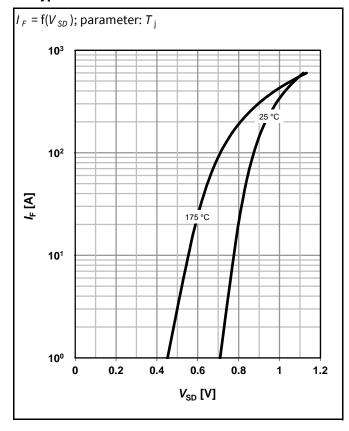
9 Typ. gate threshold voltage



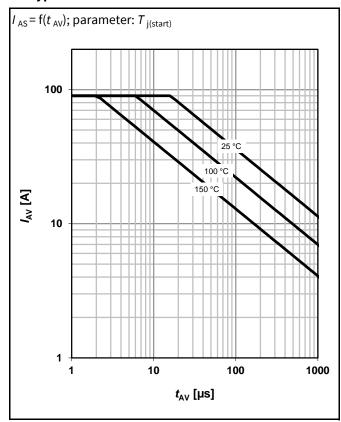
10 Typ. capacitances



11 Typical forward diode characteristics

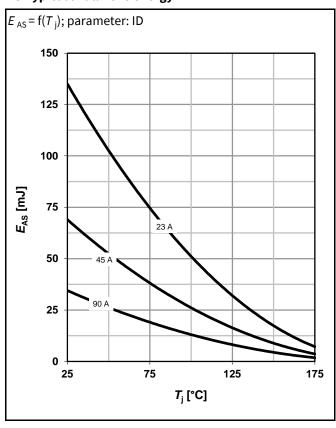


12 Typ. avalanche characteristics

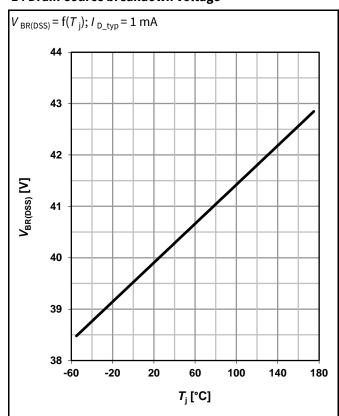


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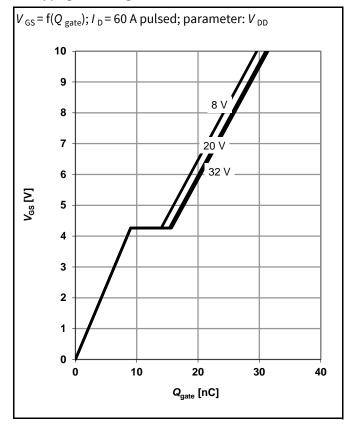
13 Typical avalanche energy



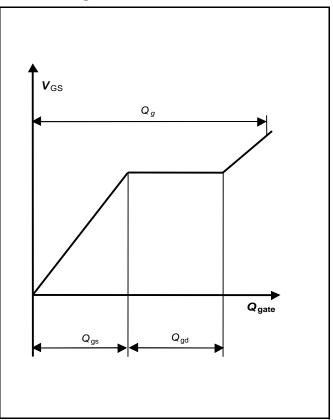
14 Drain-source breakdown voltage



15 Typ. gate charge

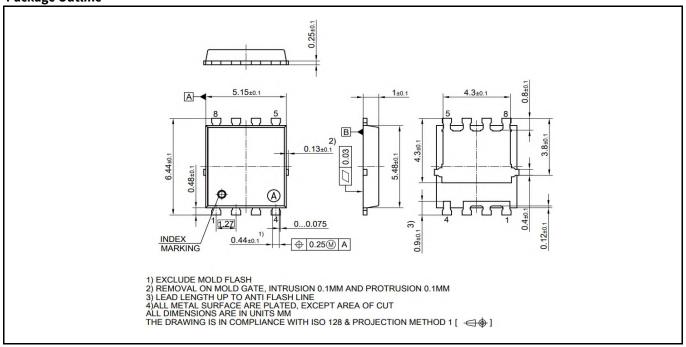


16 Gate charge waveforms



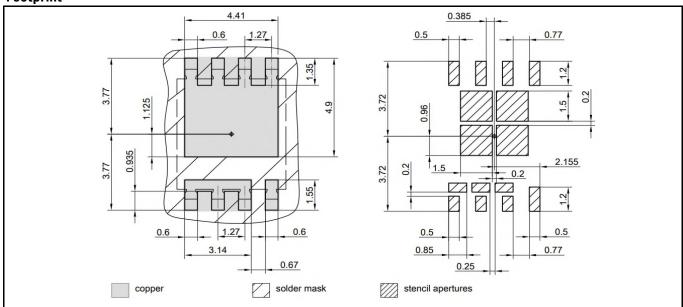


Package Outline



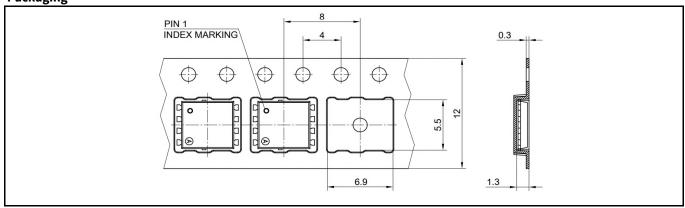
All dimensions are in units mm

Footprint



All dimensions are in units mm

Packaging



All dimensions are in units mm

IAUCN04S7N015



Revision History

Revision	Date	Changes	
Revision 1.0	15.11.2023	Final Data Sheet	

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